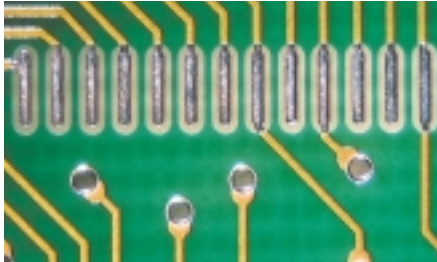


基板噴錫用(錫棒、錫絲) SN100CL

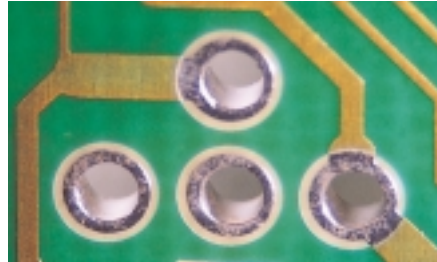
焊錫流動性與錫-鉛共晶焊錫相同，微細間距及細孔皆可均勻噴錫處理。

Hot Air Solder Leveling (HASL) SN100CL

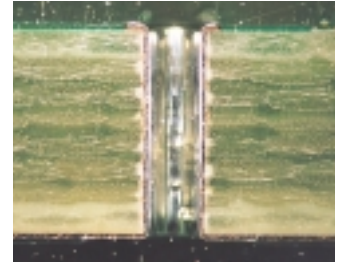
SN100CL provides a smooth bright finish and clear through holes at coating temperatures of 265°C. The SN100CL HASL process can provide the electronics industry with lead-free boards with a solderable shelf life of over a year.



無錫橋
Bridge-free coating on 0.8mm pitch pads



PAD孔內均勻光滑
Smooth uniform coating on pads and hole walls



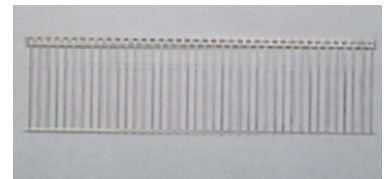
PAD、孔內及肩部鍍錫均勻
Uniform coating on pads and hole walls, even on the shoulder

電鍍陽極用(錫球、錫片、錫板) SN100CP

電解性強，錫泥發生量少，最適用於零件引腳之電鍍，並可抑制錫鬚的發生。

Anode for Electroplating (Button, Tip, Plate) SN100CP

SN100CP, available as ball, button, bar and plate anodes provides excellent performance in panel or reel-to-reel Sn-Cu plating systems providing high anode efficiency and generating very little sludge.



使用SN100CP電鍍之黃銅連接器腳
Brass connector pins electroplated with SN100CP

處理引腳末端的高溫焊錫(錫棒·錫絲) SN100C3·SN100C4

引腳線、包覆線、末端處理等高溫作業使用之無鉛焊錫。能將銅腐蝕控制在最小限度內。

For High Temperature Dip Soldering and Tinning SN100C3·SN100C4

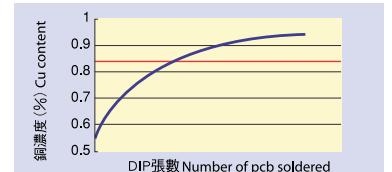
When high solder temperatures to burn insulating enamels off copper wire erosion of the copper wire can be a problem. The higher copper contents of SN100C3 and SN100C4 make it possible to carry out dip soldering with minimum copper erosion at temperature up to 400°C.

焊錫合金 溫度 400°C±4°C alloy code at 400°C±4°C	銅線平均破斷時間sec. the average of failure of copper wire.(sec.)	
	直徑 0.29mm 0.29mm diameter	直徑 0.44mm 0.44mm diameter
SN100C	32	76
SN100C3	94	160
SN100C4	119	234
Sn-Cu二元合金	31	62
SN97C	24	55
SN96CI	41	85
H63A	67	143

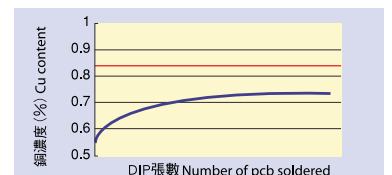
錫槽的銅成份管理方法 Managing the Copper Content of the SN100C Wave Soldering Bath

務必確實實施錫槽內之焊錫成份管理。持續使用SN100C，錫槽內的銅成份會增加。為了有效抑止錫槽內之銅濃度，須追加使用SN100Ce。銅濃度的不斷增加，是導致錫橋、錫柱、開洞、氣泡、吹孔等不良發生之原因。追加使用SN100Ce，能長期使焊錫的銅成份，維持穩定。準此，最初請先使用SN100C並建議錫槽的銅成份管理，應保持在0.6-0.85%的範圍內。

As the SN100C solder bath is used copper is dissolved from boards and component leads. If the copper content of the SN100C in the solder bath exceeds 0.85% there is likely to be an increase in the incidence of bridges, icicles and other defects. Nihon Superior have devised a simple but effective method of keeping the copper content in the optimum range of 0.6-0.85%. To replace solder carried off on the soldered boards a top-up alloy with a lower copper content, SN100Ce is used. For replacing solder removed during the skimming of dross the standard SN100C alloy can be used. Nihon Superior provide solder bath analyses to ensure that the copper content is in the recommended range.



持續使用SN100C的情形
Cu content, when SN100C is used for top-up



持續使用SN100Ce的情形
Cu content, when SN100Ce is used for top-up

SN100C 製品表

SN100C Series

型號 Products code	用途 Application	熔點 Melting point (°C)
SN100C	波峰焊、手焊 For wave soldering, manual, rework & repair	227—227
SN100Ce	用於調整錫槽內銅含量 For solder bath top-up to maintain the Cu-content	227—230
SN100CL	基板噴錫處理 For hot air solder leveling (HASL)	227—227
SN100CP	電鍍陽極 Anode for electroplating	—
SN100C3	引腳末端處理用之高溫焊錫 For high temperature dip soldering and tinning	227—310
SN100C4		227—340

